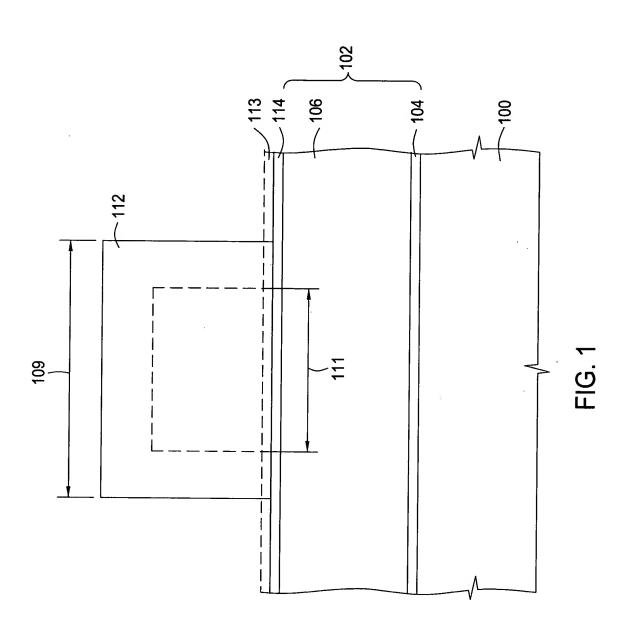
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INVENTOR: WEI LIU, ET AL.
EXPRESS MAIL NO.: EL980273124US PAGE 1 OF 4

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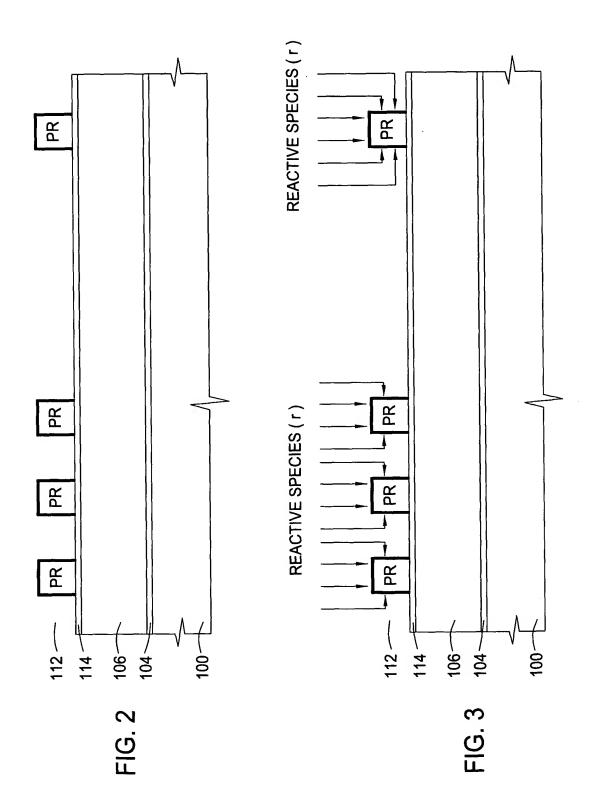
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TITLE: METHOD OF CONTROLLING CRITICAL DIMENSION MICROLOADING
OF PHOTORESIST TRIMMING PROCESS BY SELECTIVE SIDEWALL
POLYMER DEPOSITION
INVENTOR: WEILILI ET AL

INVENTOR: WEI LIU, ET AL. EXPRESS MAIL NO.: EL980273124US PAGE 2 OF 4

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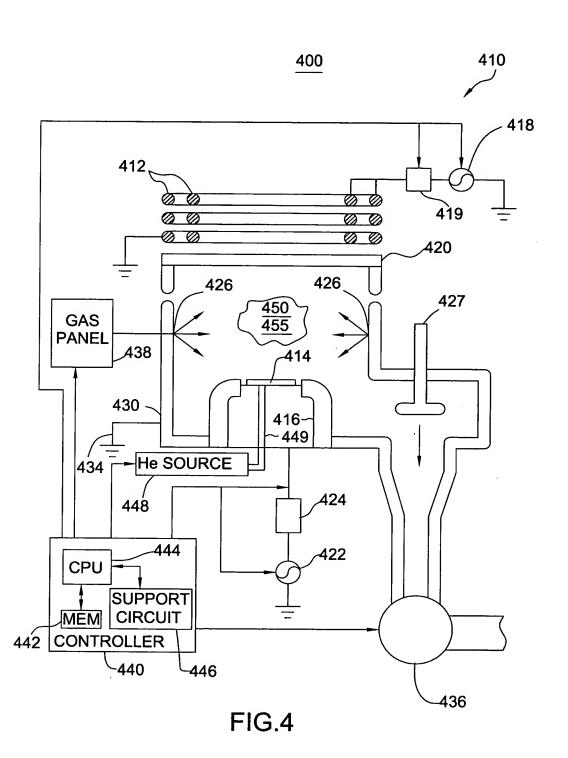
OF PHOTORESIST TRIMMING PROCESS BY SELECTIVE SIDEWALL

POLYMER DEPOSITION

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POLYMER DEPOSITION

INVENTOR: WEI LIU, ET AL.
EXPRESS MAIL NO.: EL980273124US

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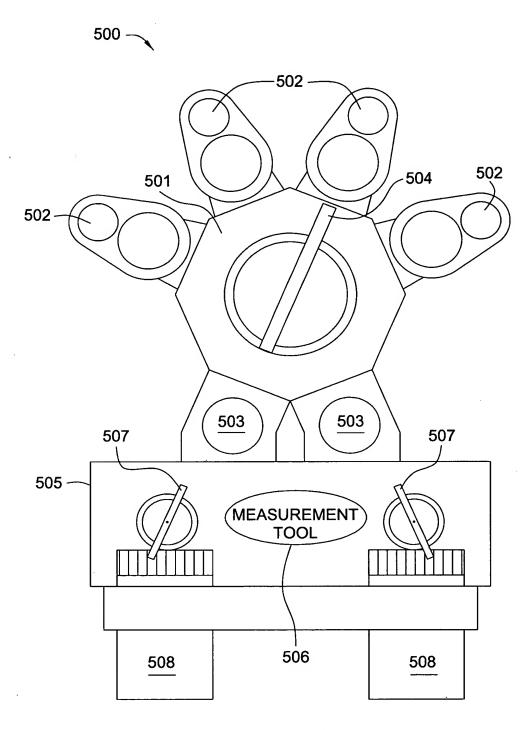


FIG. 5